

Abstract

COMPOSITIONS AND PROCESSES FOR MANUFACTURING PRINTED ELECTRONICS

The present invention is directed to a printable composition, comprising: 0.5 to 60 wt% of a polymer selected from the group consisting of epoxy, Novolac and poly(dimethylglutarimide); and 40-99.5 wt% of a solvent composition comprising (1) a high boiling point solvent having a flash point greater than about 10°C and a boiling point greater than about 130°C and (2) a low boiling point solvent having a flash point less than 30°C and a boiling point less than or equal to 130°C, all weight percents based on the total weight of the composition. The present invention is also directed to methods of forming patterned substrates using the above compositions. The compositions of the invention are useful for printing electronic materials onto a substrate using a piezo-electric printer.

Figure 1